

DSK9J01×0L

Silicon N-channel Junction FET

For low frequency amplification / For piezoelectric sensor
 DSK5J01 in SSMini3 type package

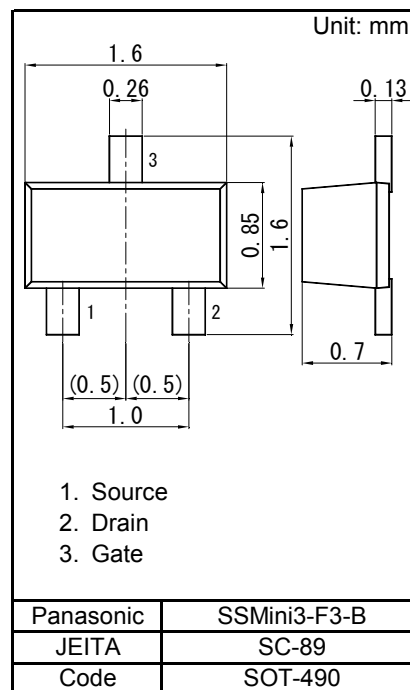
■ Features

- High gate-drain Voltage(Source open)VGDO
- Halogen-free / RoHS compliant
 (EU RoHS / UL-94 V-0 / MSL:Level 1 compliant)

■ Marking Symbol: B6

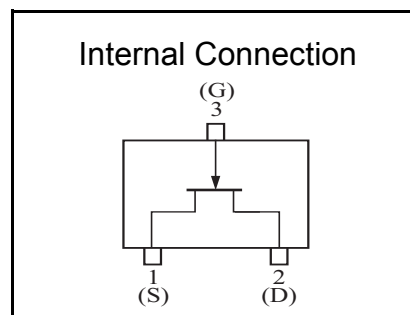
■ Packaging

Embossed type (Thermo-compression sealing) : 3 000 pcs / reel (standard)



■ Absolute Maximum Ratings Ta = 25 °C

| Parameter | Symbol | Rating | Unit |
|-----------------------------------|--------|-------------|------|
| Gate-drain voltage (Source short) | VGDS | -55 | V |
| Drain current | ID | 30 | mA |
| Gate current | IG | 10 | mA |
| Power dissipation | PD | 125 | mW |
| Channel temperature | Tch | 150 | °C |
| Operating ambient temperature | Topr | -40 to +85 | °C |
| Storage temperature | Tstg | -55 to +150 | °C |



■ Electrical Characteristics Ta = 25 °C ± 3 °C

| Parameter | Symbol | Conditions | Min | Typ | Max | Unit |
|--|--------|----------------------------------|-----|-----|-----|------|
| Gate-drain voltage (Source short) | VGDS | IG = -100 μA, VDS = 0 | -55 | | | V |
| Drain current *1 | IDSS | VDS = 10 V, VGS = 0 | 1.0 | | 6.5 | mA |
| Gate-source cutoff current | IGSS | VGS = -30 V, VDS = 0 | | | -10 | nA |
| Gate-source cutoff voltage | VGSC | VDS = 10 V, ID = 10 μA | | | -5 | V |
| Forward transfer admittance | Yfs | VDS = 10 V, ID = 5 mA, f = 1 kHz | 2.5 | 7.5 | | mS |
| Small-signal short-circuit input capacitance | Ciss | VDS = 10 V, VGS = 0, f = 1 MHz | | 6.0 | | pF |
| Small-signal reverse transfer capacitance | Crss | | | 2.5 | | pF |

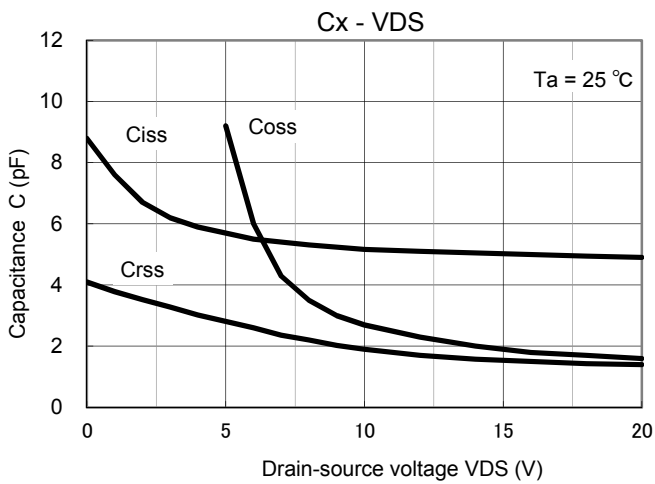
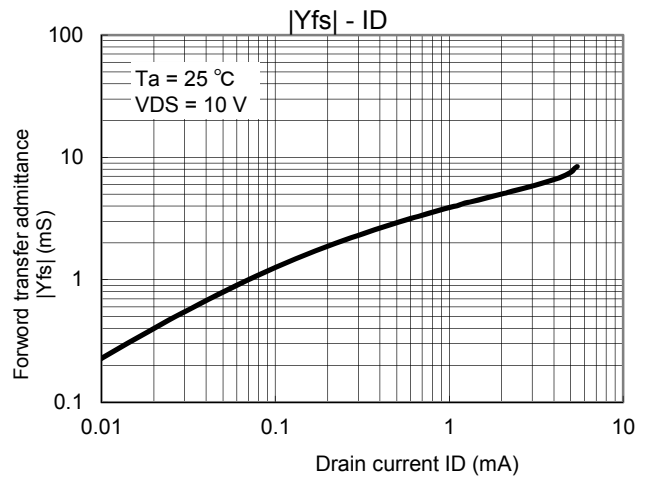
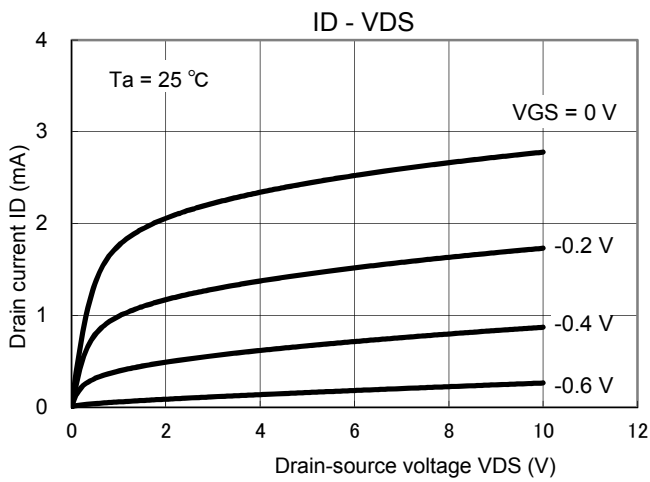
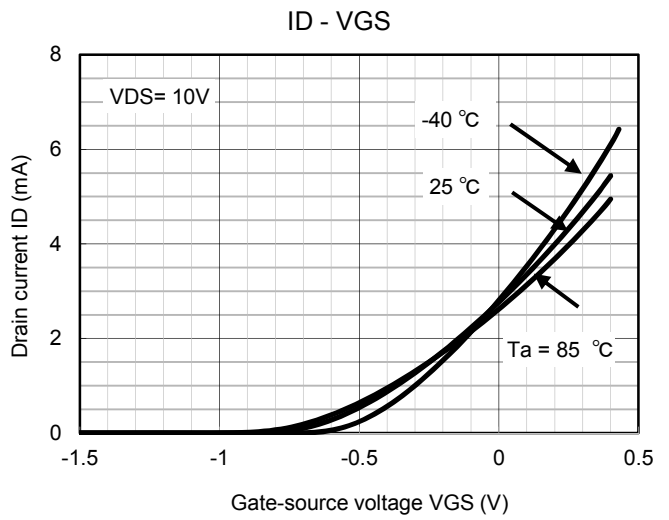
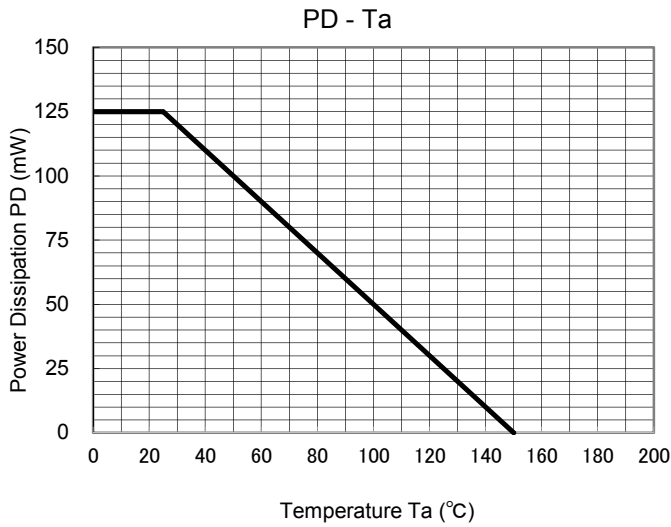
Note) Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 Measuring methods for transistors.

*1 Rank classification

| Code | P | Q |
|----------------|------------|------------|
| Rank | P | Q |
| IDSS (mA) | 1.0 to 3.0 | 2.0 to 6.5 |
| Marking symbol | B6P | B6Q |



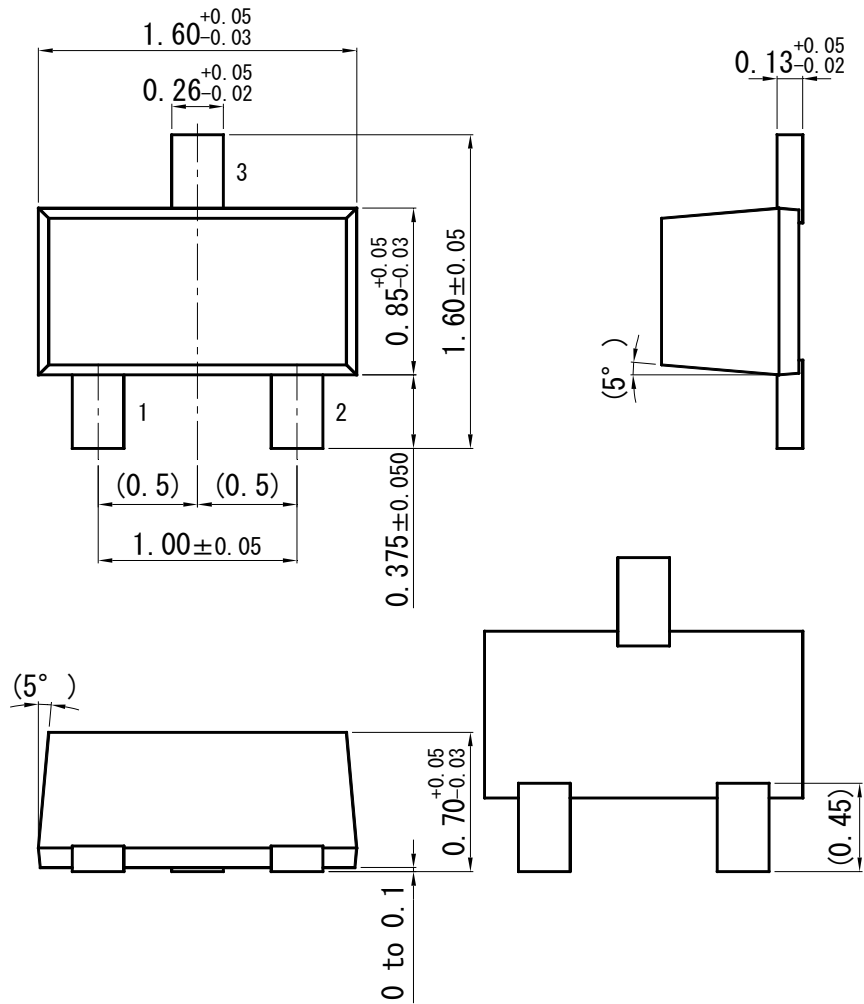
Technical Data (reference)



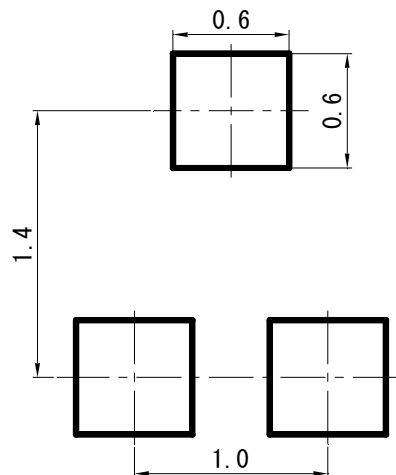
Panasonic

SSMini3-F3-B

Unit: mm



■ Land Pattern (Reference) (Unit: mm)



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